

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10761690			
<b>Filing Date:</b>	20-Jan-2004			
<b>Title of Invention:</b>	SYSTEM AND METHOD FOR ACHIEVING PLANAR ALIGNMENT OF A SUBSTRATE DURING SOLDER BALL MOUNTING FOR USE IN SEMICONDUCTOR FABRICATION			
<b>First Named Inventor:</b>	Art Bayot			
<b>Filer:</b>	Yingsheng Tung/Jackie McBride			
<b>Attorney Docket Number:</b>	TI-33355A			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700